



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 4981  
Hiroshi TAKANASHI et al. : Docket No. 2000-1749  
Serial No. 09/739,750 : Group Art Unit 1752  
Filed December 20, 2000 : Examiner S. Lee

NEGATIVE-WORKING PHOTORESISTIVE  
RESIN COMPOSITION AND PHOTORESISTIVE  
RESIN PLATE USING THE SAME

RECEIVED  
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1C 1100 MAIL ROOM  
9/22/02  
THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975

**RESPONSE TO FINAL REJECTION**

Assistant Commissioner for Patents,  
Washington, D.C.

**RESPONSE UNDER 37. CFR 1.116**  
**EXPEDITED PROCEDURE**  
**EXAMINING GROUP 1752**

Sir:

In response to the Official Action dated June 19, 2002, the period for response having been extended for two months by the attached petition, please amend the present application as follows:

**IN THE SPECIFICATION**

*Please rewrite paragraph [0056] as follows:*

**[0056] EXAMPLES 1 - 17:**

(i) Preparation of water-soluble photosensitive resin compositions 1-17:

In 200 parts by weight of water was dissolved 200 parts by weight of polyvinyl alcohol (degree of saponification: 70%, degree of polymerization: 500) as component (A), and then 70 parts by weight of polyethylene glycol diacrylate as component (B), 4 parts by weight of benzylidemethyl ketal as component (C), 0.1 part by weight of methylhydroquinone as component (D), and X parts by weight (X: addition amount indicated in Table I below) of p-toluenesulfonamide were added as component (E) to the solution to prepare water-soluble photosensitive resin compositions 1 - 17.

Please enter  
E.S. ✓